Advanced Electronics Inc.

DESIGN SPECIFICATIONS

Materials

Tetra-functional, Multi-functional, FR-4, FR-5, Polyimide, G-Tek, Rogers
All meet IPC-4101

Maximum Panel Size

Negotiable

Lamination

Maximum Layer Count:	12
Maximum Board Thickness	250 mils
Minimum Board Thickness	14 mils

Panel Thickness Tolerance

.011 - .040	+/- .004
.041 - .066	+/- .0051
.067 - .100	+/- .007
.101 - .140	+/- .009
.141 - .250	+/- .012

Bow & Twist

7.5 mils/inch

Prepreg

Tetra-functional, HG Multi-functional
Glass types used: 106, 1080, 2113, 2116, 7628
All meet IPC-4101

Inner Layer Copper Cladding

Maximum Cu Weight:	Planes	6 oz
	Signals	6 oz
Minimum Cu Weight:		.25 oz

Inner Layer Minimum Line & Space

Cu	Width
.25 oz	5 mil
.5 oz	5 mil
1 oz	5 mil
2 oz	6 mil

Inner Layer Annular Ring

Component Pads: PTH	6 mils over drilled
Via Pads: PTH	5 mils over drilled
Clearance(antipads): PTH	12 mils over drilled
NPTH	10 mils over drilled

Outer Layer Copper Cladding

Maximum Cu Weight	6 oz
Minimum Cu Weight	.25 oz

Layer Construction/Impedance

Minimum Core Thickness	5 mils
Finished Impedance Tolerance:	+/- 10%

Blind & Buried Vias

Outer Layer Minimum Line & Space

Cu	Width
.25 oz	5 mil
.5 oz	5 mil
1 oz	5 mil
2 oz	6 mil

Feature to Boards Edge Minimum

Outer Layer	5 mil
Inner Layer	10 mil

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